

Class 1-29/832, 31/7/02  
A method to

1 7. The method of claim 1, wherein said daughter-card support allows hand  
2 replacement of one or more daughter-card substrates.

1 8. A method to fabricate a daughter-card support, comprising:  
 2 selecting a set of physical dimensions of said daughter-card support;  
 3 modeling said daughter-card support after insertion of a daughter-card substrate;  
 4 estimating a more precise set of physical dimensions for said daughter-card  
 5 support after modeling said daughter-card support with an inserted daughter-card  
 6 substrate; and  
 7 shaping said daughter-card support according to said more precise set of  
 8 physical dimensions.

1 9. The method of claim 8, wherein said motherboard substrate and said one or  
 2 more daughter-card substrates are selected from the group of substrates consisting of: a  
 3 printed circuit board (PCB), a multi-chip module (MCM), and a flexible substrate.

1 10. The method of claim 8, wherein said daughter-card support further comprises  
 2 one or more electrical connections to a daughter-card.

1 11. The method of claim 8, wherein said daughter-card support is fabricated from a  
 2 material selected from the group of materials consisting of: a stainless steel alloy, a  
 3 magnesium alloy, an aluminum alloy, a plastic, or a composite.

1 12. The method of claim 8, wherein said daughter-card support has one or more L-  
 2 shaped brackets to hold one or more card edges of said one or more daughter-cards.

1 ~~13.~~ An assembled substrate, comprising:  
 2 a motherboard substrate, including one or more electrical components;  
 3 one or more daughter-card substrates, wherein at least one of said daughter-card  
 4 substrates includes one or more electrical components; and  
 5 a daughter-card support to structurally support said one or more daughter-card  
 6 substrates in fixed orientations relative to said motherboard substrate.

1 14. The assembled substrate of claim 13, wherein said motherboard substrate and  
 2 said one or more daughter-card substrates are selected from the group of substrates  
 3 consisting of: a printed circuit board (PCB), a multi-chip module (MCM), and a  
 4 flexible substrate.

1 15. The assembled substrate of claim 13, wherein said daughter-card support further  
 2 comprises one or more electrical connections to a daughter-card.

1 16. The assembled substrate of claim 13, wherein said daughter-card support is  
 2 fabricated from a material selected from the group of materials consisting of: a  
 3 stainless steel alloy, a magnesium alloy, an aluminum alloy, a plastic, or a composite.

1 17. The assembled substrate of claim 13, wherein said daughter-card support has a  
 2 "spine and rib" style of architecture.

1 18. The assembled substrate of claim 13, wherein said daughter-card support has  
 2 one or more L-shaped brackets to hold one or more card edges of said one or more  
 3 daughter-cards.

1 19. The assembled substrate of claim 13, wherein said daughter-card support allows  
 2 hand replacement of ~~one~~ or more daughter-card substrates.

1 20. The assembled substrate of claim 13, wherein said daughter-card support has a  
 2 plurality of air-flow channels, wherein each air-flow channel includes one or more  
 3 holes.

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